Variant: 001
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TIDA-01341 REV A1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1	2	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0402	0402
2	C2	2	1uF	C1005X5R1E105K050BC	TDK	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0402	0402
3	C3, C3, C6, C6	4	820pF	GRM1885C2A821JA01D	MuRata	CAP, CERM, 820 pF, 100 V, +/- 5%, C0G/NP0, 0603	0603
4	C4, C4, C5, C5	4	0.1uF	GRM188R71E104KA01D	MuRata	CAP, CERM, 0.1 µF, 25 V, +/- 10%, X7R, 0603	0603
5	CBAT	2	10uF	C1608X5R1A106M080AC	TDK	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0603	0603
6	CCPOUT	2	4.7uF	C0603C475K9PACTU	Kemet	CAP, CERM, 4.7 µF, 6.3 V, +/- 10%, X5R, 0603	0603
7	COUT+, COUT+, COUT-, COUT-	4	2.2uF	C1608X5R0J225M	TDK	CAP, CERM, 2.2 µF, 6.3 V, +/- 20%, X5R, 0603	0603
8	H9, H10, H11, H12	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
9	J1	2		970	Keystone	RCA Jack, White, R/A, TH	PC Mount Phono Jack-White, TH
10	J2	2		971	Keystone	RCA Jack, Red, R/A, TH	PC Mount Phono Jack-Red, TH
11	J3, J3, J7, J7	4		TSW-103-07-G-D	Samtec	Header, 100mil, 3x2, Gold, TH	3x2 Header
12	J4, J4, J9, J9, J10, J10, J11, J11, J15, J15, J18, J18, J20, J20	14		HMTSW-102-07-G-S-240	Samtec	Header, 100mil, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
13	J5, J5, J6, J6	4		SJ-3523-SMT	CUI Inc.	Audio Jack, 3.5mm, Stereo, R/A, SMT	Audio Jack SMD
14	J8, J8, J16, J16, J17, J17, J19, J19	8		TSW-106-07-G-S	Samtec	Header, 100mil, 6x1, Gold, TH	6x1 Header
15	J12, J12, J13, J13	4		112404	Amphenol Connex	Connector, TH, BNC	Amphenol_112404
16	J14	2		TSW-104-07-G-D	Samtec	Header, 100mil, 4x2, Gold, TH	4x2 Header
17	J21	2		HTSW-103-09-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	Header, 3x1, 2.54mm, TH
18	R1, R1, R3, R3	4	243k	CRCW0603243KFKEA	Vishay-Dale	RES, 243 k, 1%, 0.1 W, 0603	0603
19	R2, R2, R4, R4	4	76.8k	CRCW060376K8FKEA	Vishay-Dale	RES, 76.8 k, 1%, 0.1 W, 0603	0603
20	R5, R5, R6, R6, R7, R7, R9, R9	8	1.00k	ERJ-P06F1001V	Panasonic	RES, 1.00 k, 1%, 0.25 W, 0805	0805
21	R11, R11, R12, R12, R15, R15	6	16.0	ERJ-P06F16R0V	Panasonic	RES, 16.0, 1%, 0.5 W, 0805	0805
22	R13	2	604	ERJ-P06F6040V	Panasonic	RES, 604, 1%, 0.5 W, 0805	0805
23	R14	2	1.20k	ERJ-P06F1201V	Panasonic	RES, 1.20 k, 1%, 0.5 W, 0805	0805
24	R16	2	10.0k	ERJ-3EKF1002V	Panasonic	RES, 10.0 k, 1%, 0.1 W, 0603	0603
25	SH-J2	1	1x2	969102-0000-DA	3M	Shunt, 100mil, Gold plated, Black	Shunt
26	U1	2		OPA1622IDRCR	Texas Instruments	SoundPlus High-Fidelity, Bipolar-Input, Audio Operational Amplifier, DRC0010J	DRC0010J
27	U2	2		LM27762DSSR	Texas Instruments	Low-Noise Regulated Switched-Capacitor Voltage Inverter and Positive LDO, DSS0012B	DSS0012B
28	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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